

PMP30296 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1	1	22uF	GRM32ER71E226KE15L	MuRata	CAP, CERM, 22 μ F, 25 V,+/- 10%, X7R, 1210	1210
C2	1	1uF	GRM188R71E105KA12D	MuRata	CAP, CERM, 1 μ F, 25 V,+/- 10%, X7R, 0603	0603
C3	1	10uF	GRM31CR71E106KA12L	MuRata	CAP, CERM, 10 μ F, 25 V,+/- 10%, X7R, 1206	1206
C4	1	100uF	GRM32ER60J107ME20L	MuRata	CAP, CERM, 100 μ F, 6.3 V,+/- 20%, X5R, 1210	1210
C5	1	39pF	GRM1885C1H390JA01D	MuRata	CAP, CERM, 39 pF, 50 V,+/- 5%, C0G/NP0, 0603	0603
C6, C7	2	0.1uF	GRM188R71E104KA01D	MuRata	CAP, CERM, 0.1 μ F, 25 V,+/- 10%, X7R, 0603	0603
D1	1	30V	DB3X316N0L	Panasonic	Diode, Schottky, 30 V, 0.1 A, SOT-23	SOT-23
D2	1	20V	MBR1020VL	Fairchild Semiconductor	Diode, Schottky, 20 V, 1 A, SOD-123F	SOD-123F
J1, J3	2		ED555/2DS	On-Shore Technology	Terminal Block, 6A, 3.5mm Pitch, 2-Pos	7.0x8.2x6.5mm THT
J2	1		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin, THT	Header, 3 PIN, 100mil, Tin
L1	1	2.2uH	LPD5030-222ME	Coilcraft	Coupled inductor, 2.2 μ H, 1.95 A, 0.034 ohm	4.8x4.8x2.9mm SMD
R1	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9, 1%, 0.1 W, 0603	0603
R2	1	499k	CRCW0603499KFKEA	Vishay-Dale	RES, 499 k, 1%, 0.1 W, 0603	0603
R3	1	90.9k	CRCW060390K9FKEA	Vishay-Dale	RES, 90.9 k, 1%, 0.1 W, 0603	0603
R4	1	150k	CRCW0603150KFKEA	Vishay-Dale	RES, 150 k, 1%, 0.1 W, 0603	0603
TP1, TP5	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP2, TP4	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
TP3	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		LMR61428MM/NOPB	Texas Instruments	Low Input Voltage, Step-Up DC-DC, 8-pin MSOP	MUA08A

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